



FARADAY 
TECHNOLOGY, INC.

2023 Blum Lecture:

Technics in Boundary Layer and Surface Chemistry Control

Dr Timothy Hall



UNIVERSITY OF
NOTRE DAME



TimHall@FaradayTechnology.com

Outline

- First 20 years
 - WVU (Dr. John Zondlo)
 - Notre Dame (Dr. Albert Miller) / NuVant Systems
 - Faraday (EJ Taylor)
- Next 20 years
 - New materials and uses
 - Bring material processing back to the US
 - Training the next generation



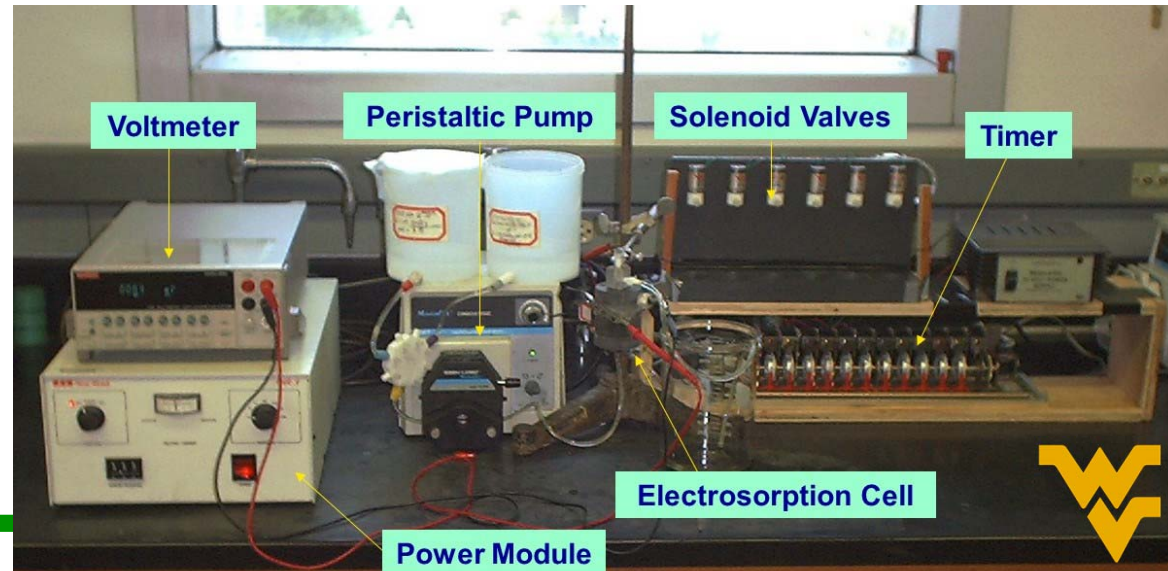
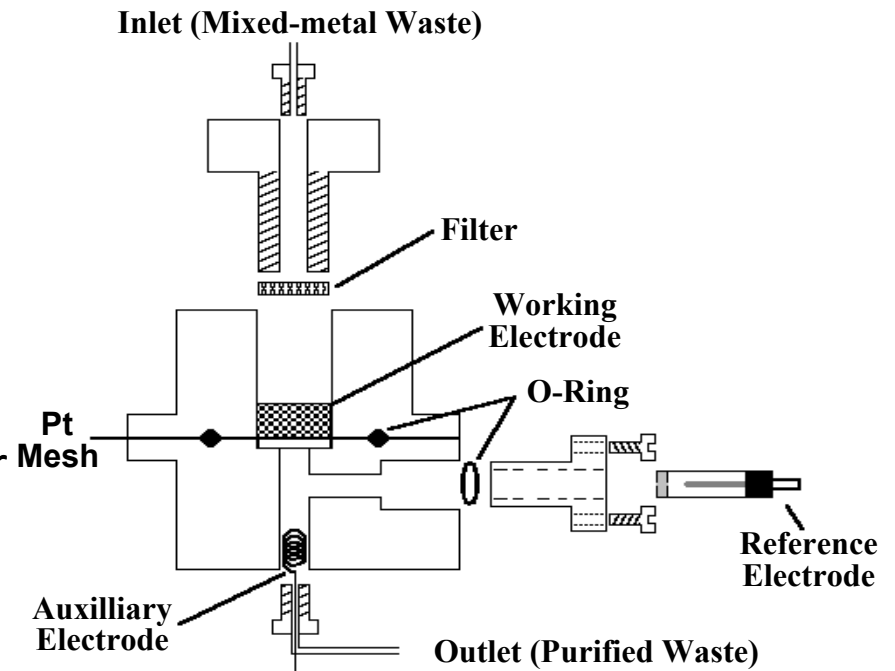
WVU (2001 to 2003)

Electrosorption method for uranyl filtration from ground water streams

- First exposure to electrochemistry
 - Critical parameters that would become key for future work
 - Electrochemical induced pH changes near a high surface area electrode surface

Key findings:

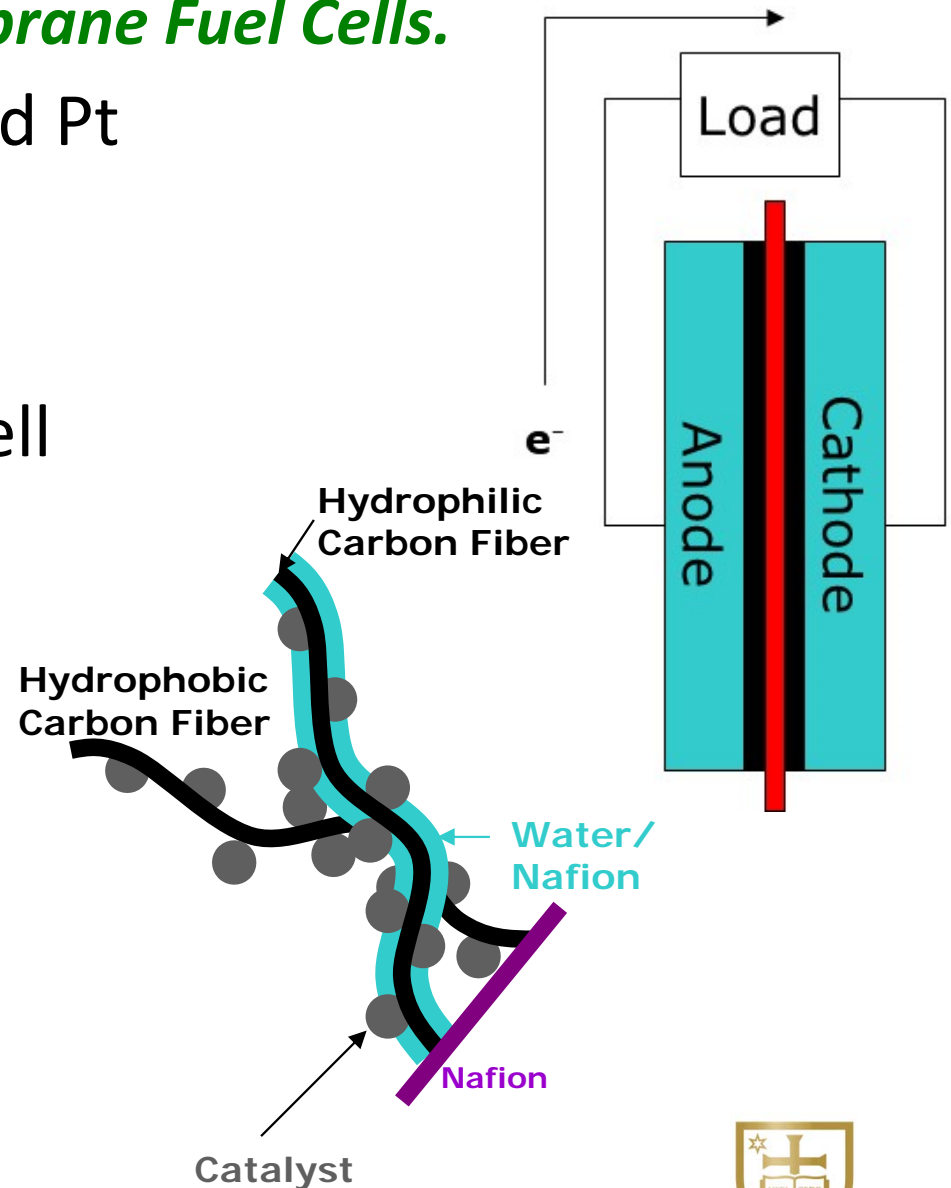
- Electrolyte pH and applied voltage critical to absorption capacity
- Density of working electrode affected capacity
- System was inherently reversible by changing polarity.
- System is recoverable



ND (2003 – 2007)

Catalyst and Microporous Layer Design for Low Temperature Polymer Electrolyte Membrane Fuel Cells.

- Pulse electrodeposition of Pt and Pt alloys
- Water management design
- Combinatorial analysis of fuel cell performance
 - Direct methanol (DMFC)
Anode: $\text{CH}_3\text{OH} + \text{H}_2\text{O} \rightarrow 6\text{H}^+ + \text{CO}_2 + 6\text{e}^-$
Cathode: $\text{O}_2 + 4\text{H}^+ + 4\text{e}^- \rightarrow 2\text{H}_2\text{O}$
 - H_2 fueled (PEMFC)
Anode: $\text{H}_2 \rightarrow 2\text{H}^+ + 2\text{e}^-$



ND (Pulse Deposition)

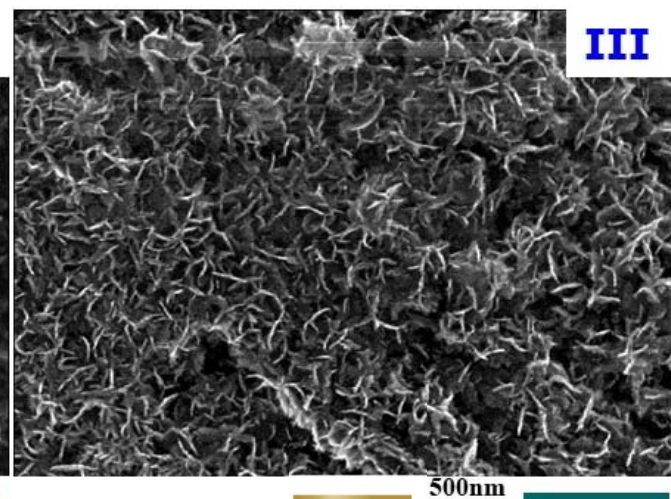
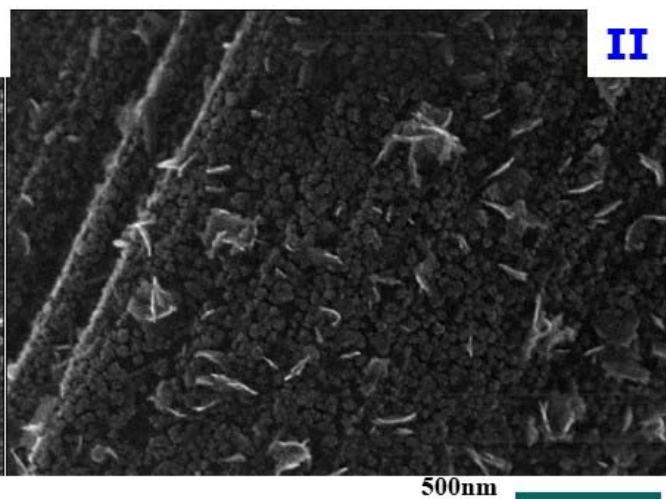
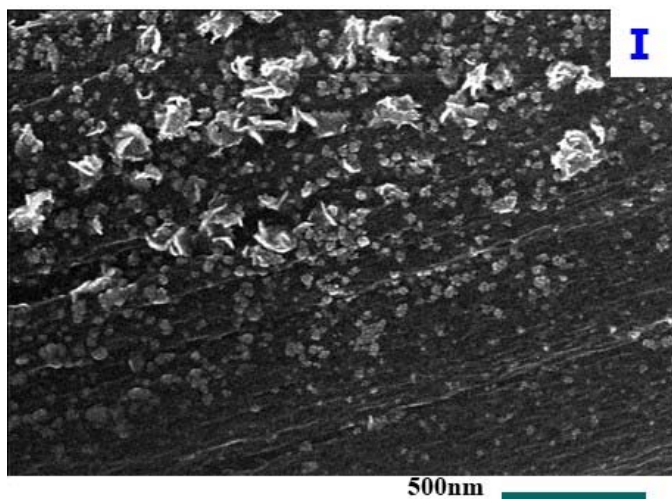
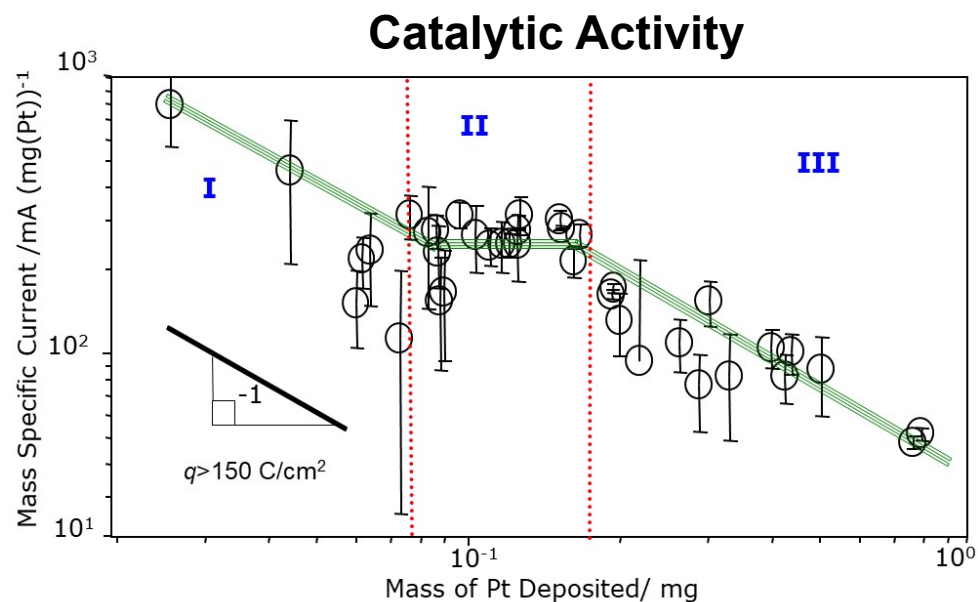
Potential to Control the Boundary Layer and Catalyst Structure with Pulse

- Shows a broad range of Pt masses that achieve nearly identical activity for DMFC

I: Nucleation: 

II: Lateral Growth: 

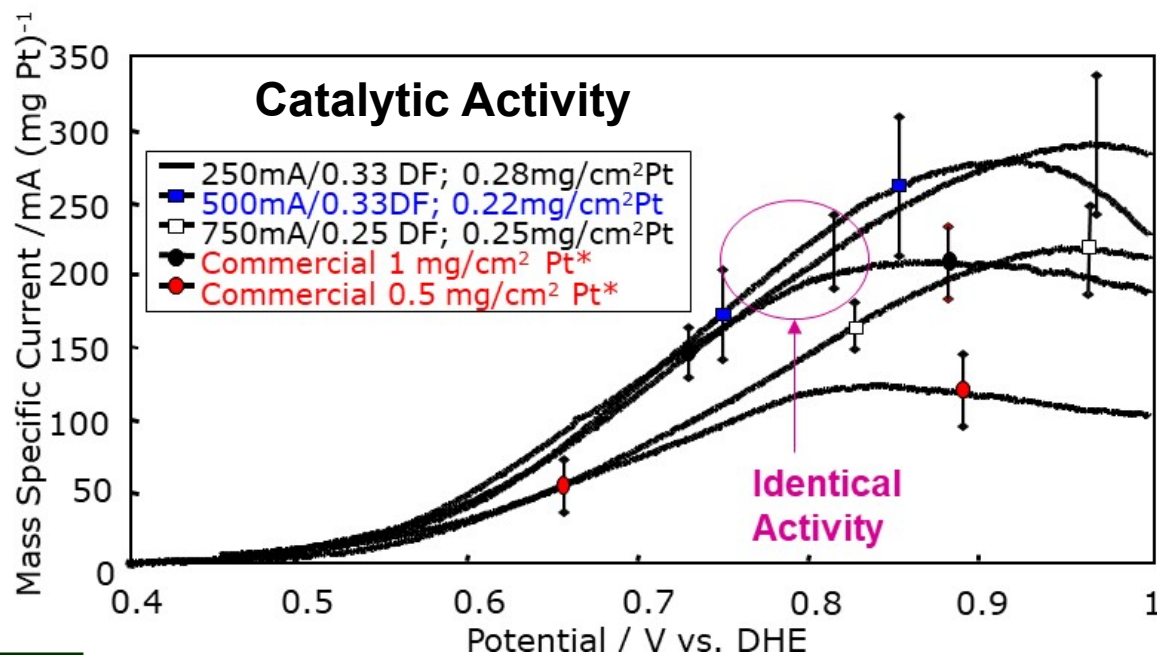
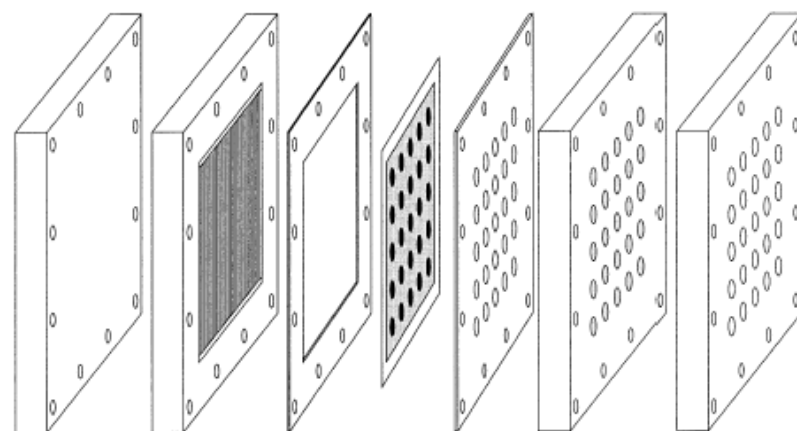
III: Vertical Growth: 



ND/NuVant Systems (2007-2009)

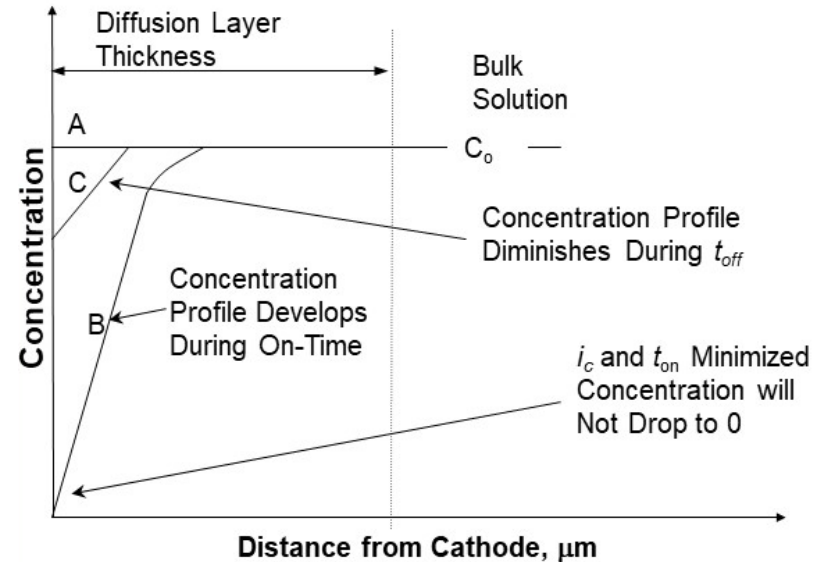
Combinatorial Electrochemical Characterization

- Used NuVant Systems Arraystat
- Showed improved electrocatalyst performance using PP Pt
- Led to my first professional job



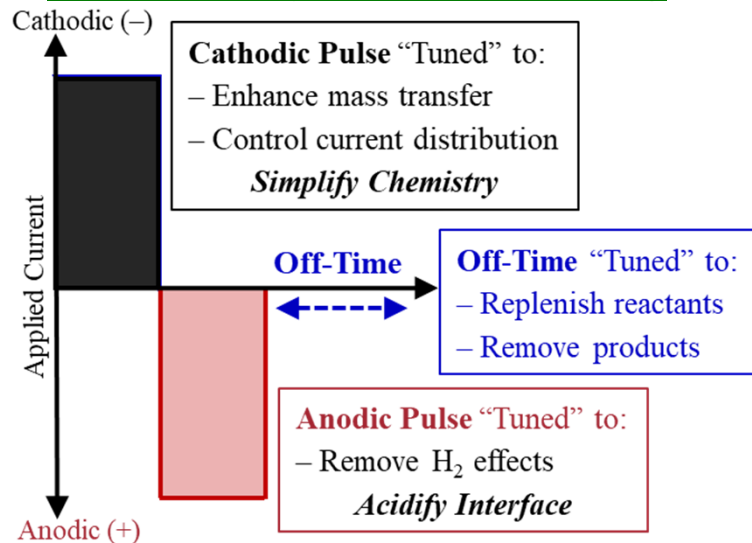
Faraday Technology (2009 to Present)

- Interest in
 - Electrochemistry
 - Electrochemical system design
 - Electronics
 - Boundary layer control
 - Pulse control

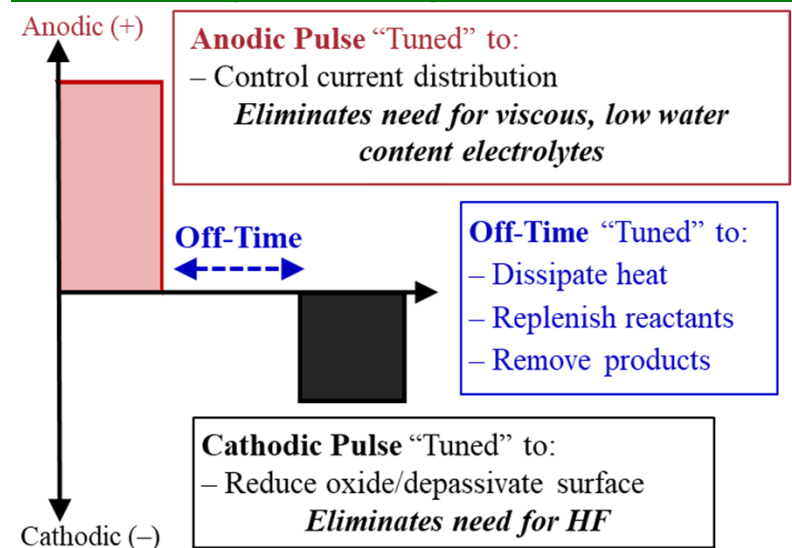


Led me to Faraday

Electrodeposition/Plating

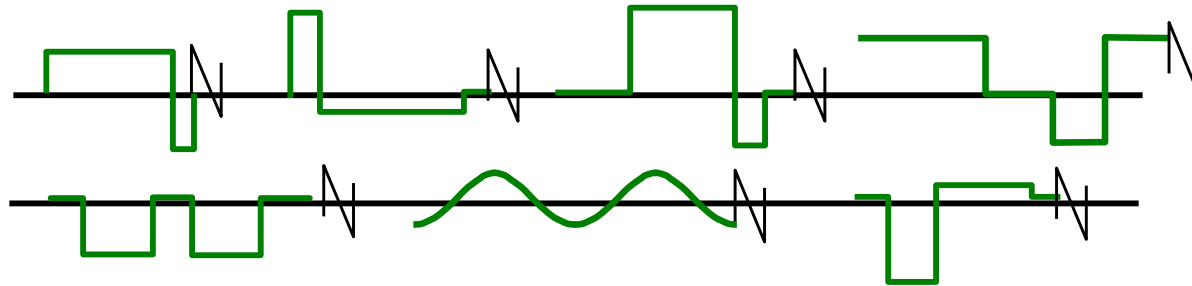


Electrochemical Machining, Polishing, Deburring, Through-Mask Etching





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Pulse Deposition

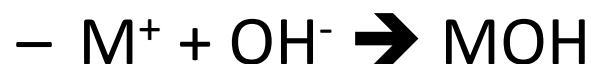
Pulse Electrodeposition

- Generally, multiple reductions occur at the cathode

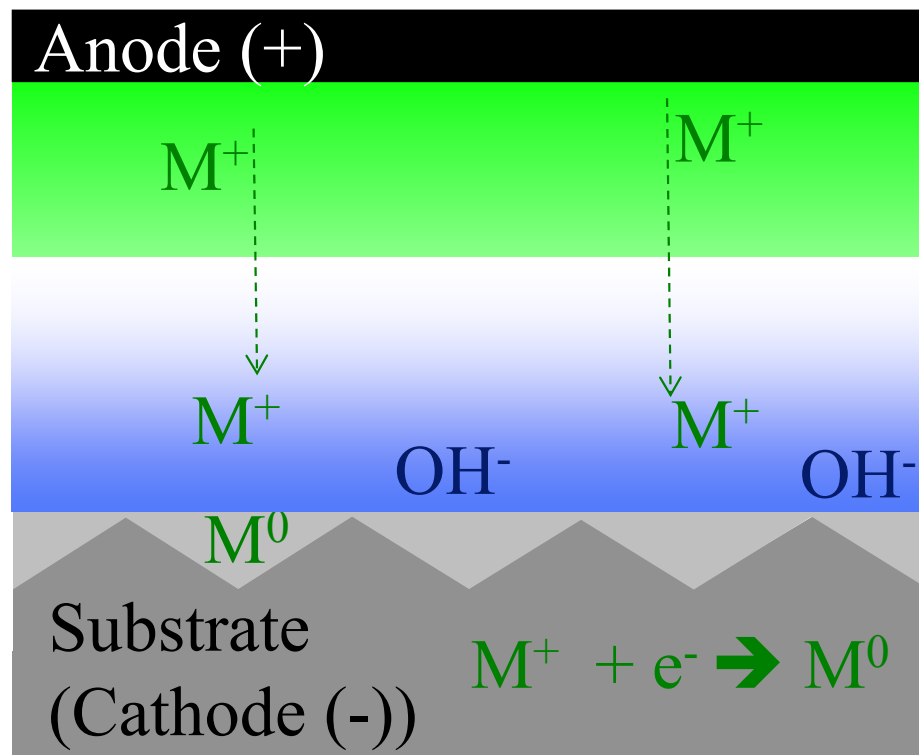
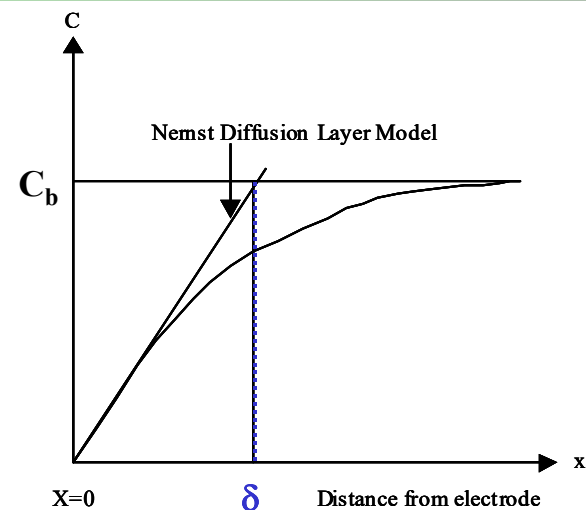


- (when efficiency <100%)

- Local pH change can lead to side reactions



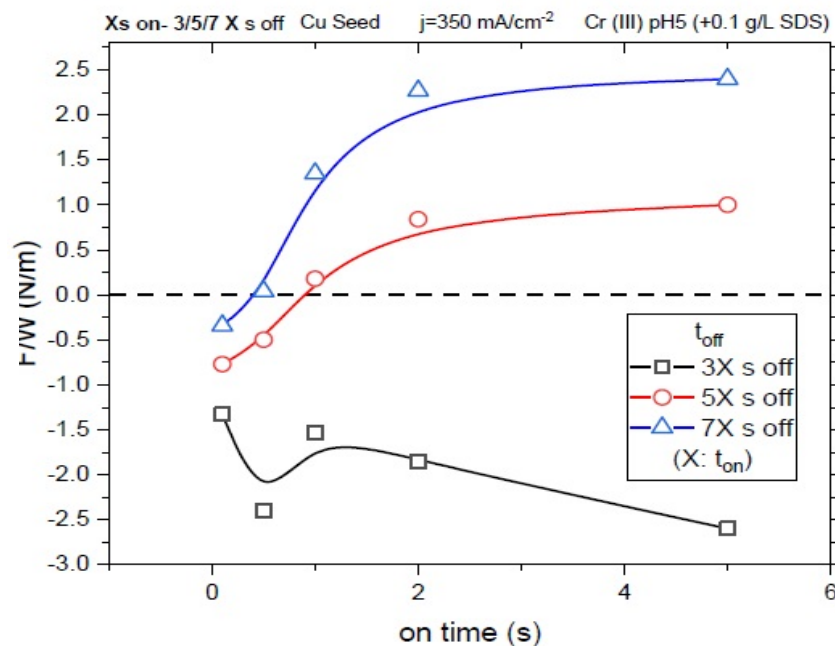
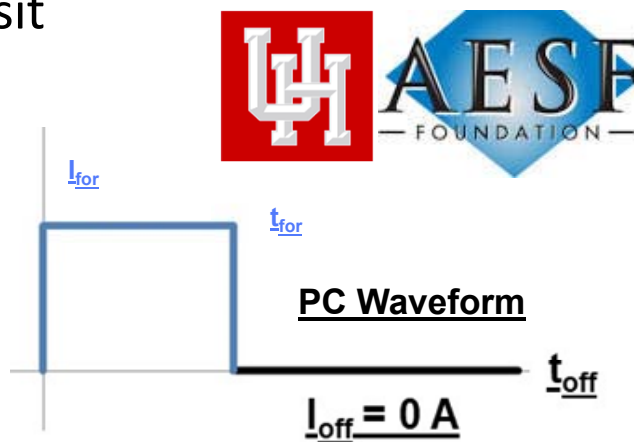
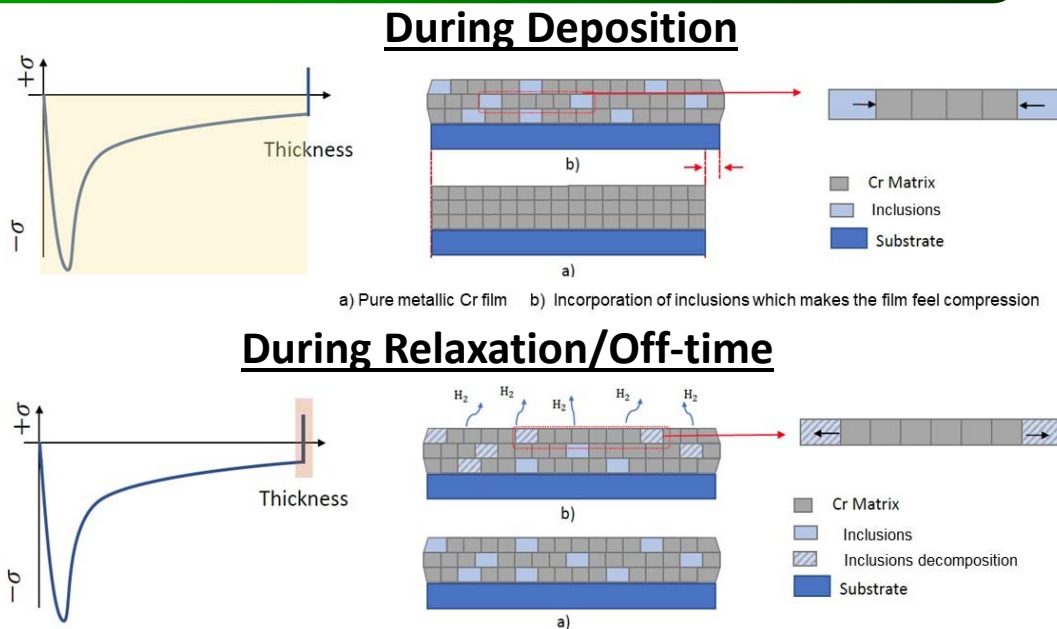
❖ Need to consider the pH change in the boundary layer as well as the concentration gradient in the diffusion layer



Pulse Electrodeposition with Single Metal

- Cr plating is an excellent example of side reaction affect
 - Efficiency less than 15%
 - Local CrOH formation
 - High current density leads to complexant break down
 - Inclusions of C, O, and presumably H in the deposit

<https://www.pfonline.com/article/s/nasfaesf-university-funded-research-transitioned-to-industry-practical-performance-improvements-in-functional-reach-compliant-trivalent-chromium-plating>



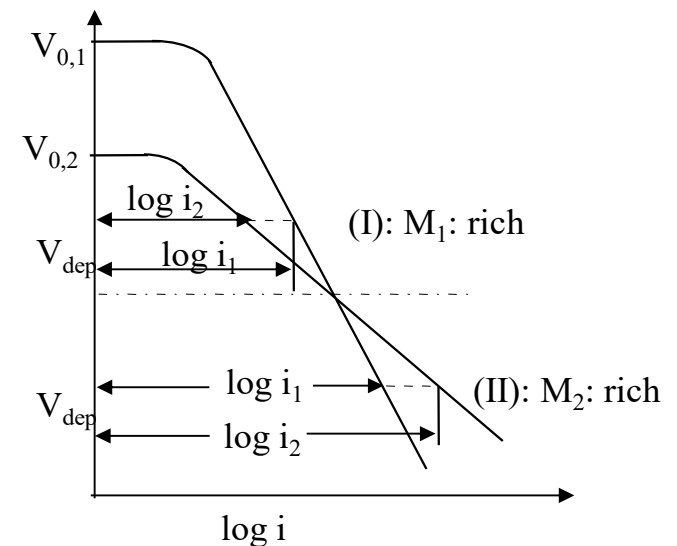
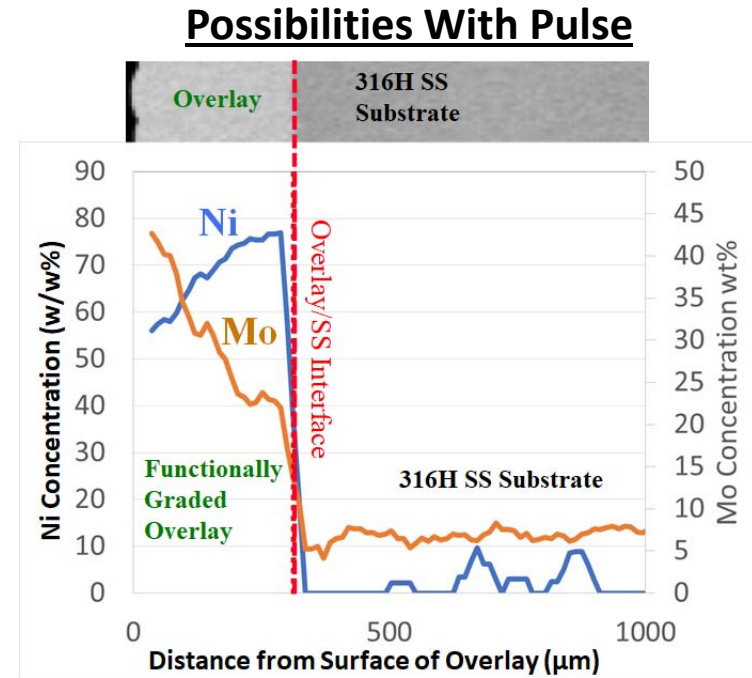
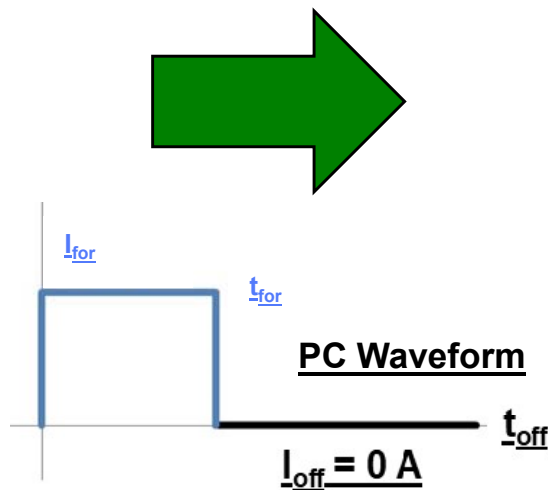
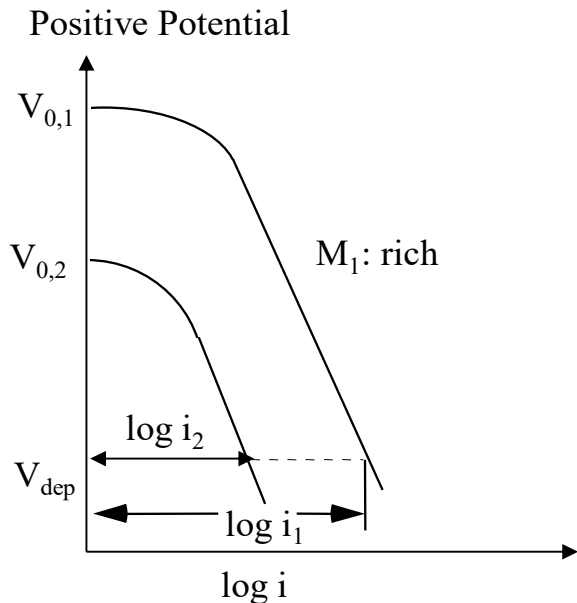
Pulse with Alloy Metal Electrodeposition

- Functionally graded NiMo coating

- 0.2 M Ni
- 0.02 M Mo

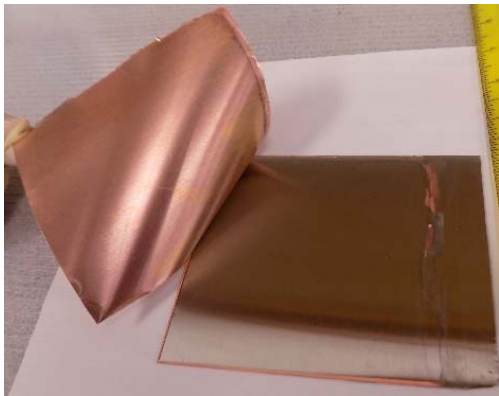
❖ Without electrolyte change large composition variance just with small duty cycle changes.

Anticipated Deposition w/DC

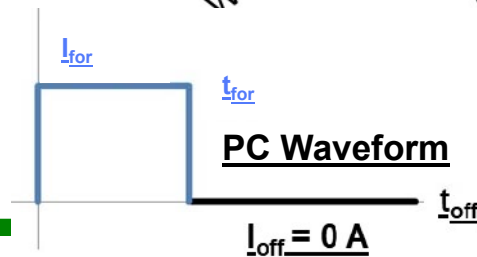
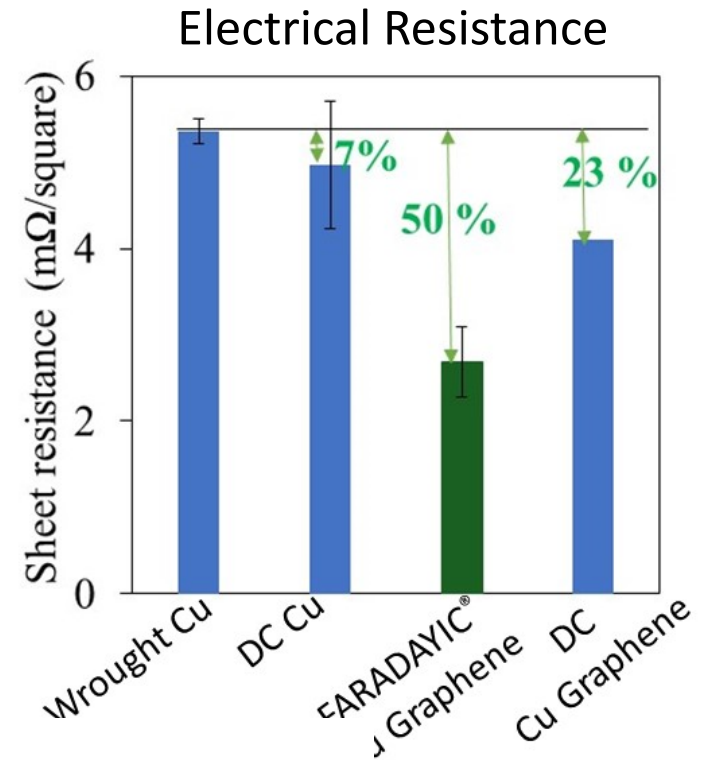
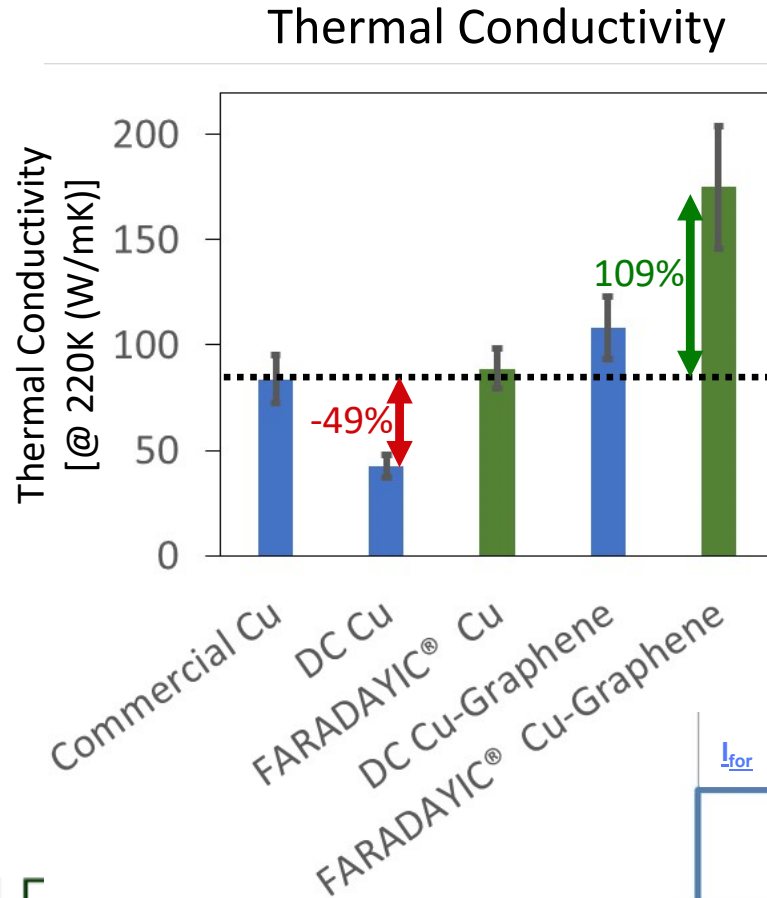


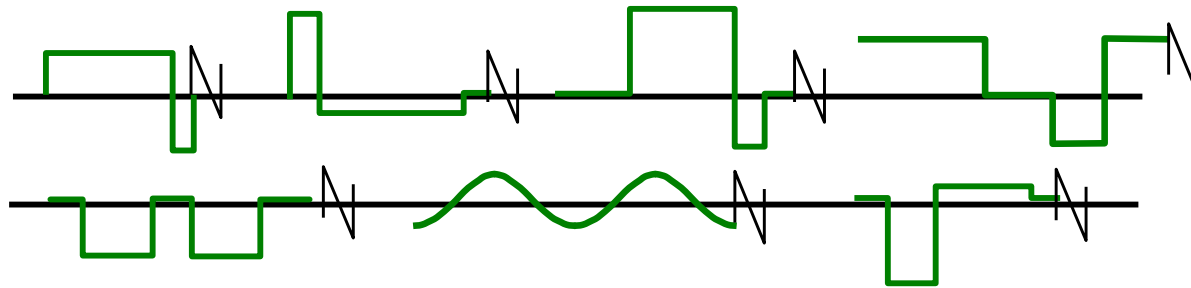
Pulse with Composite Electrodeposition

- Graphene inclusion concentration control leads to enhanced electrical/ thermal conductivity
- ❖ Small on-time and off-time changes lead to large inclusion effect



Cu/Graphene Foil

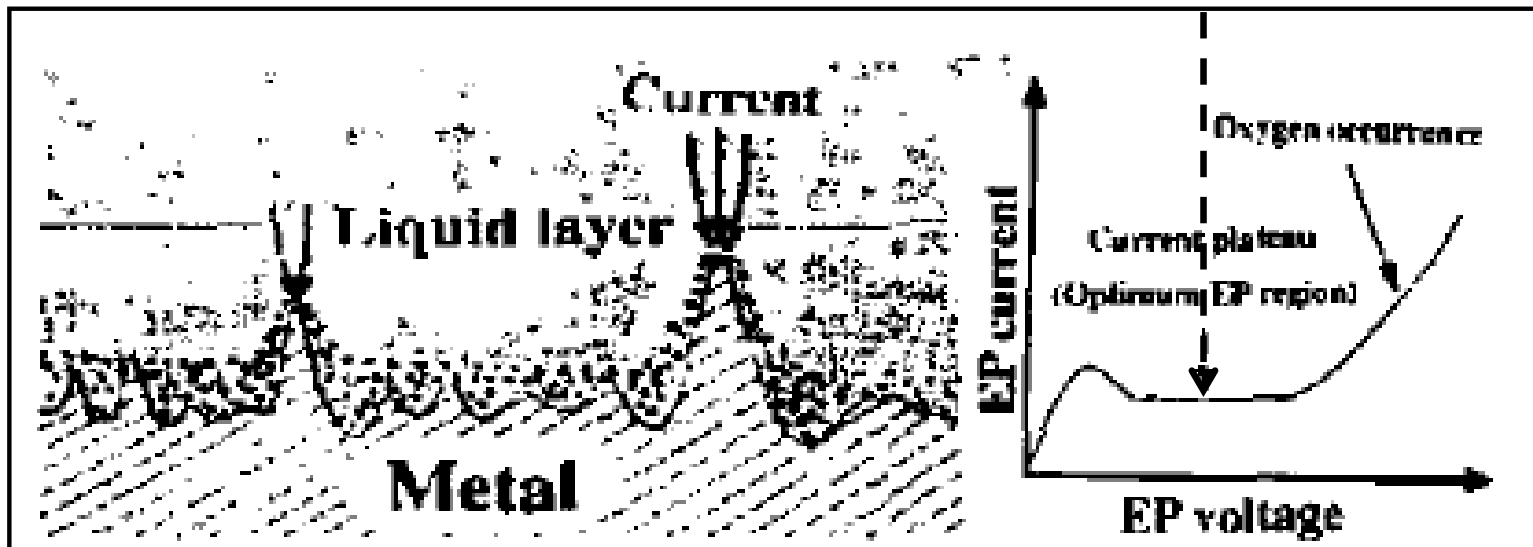
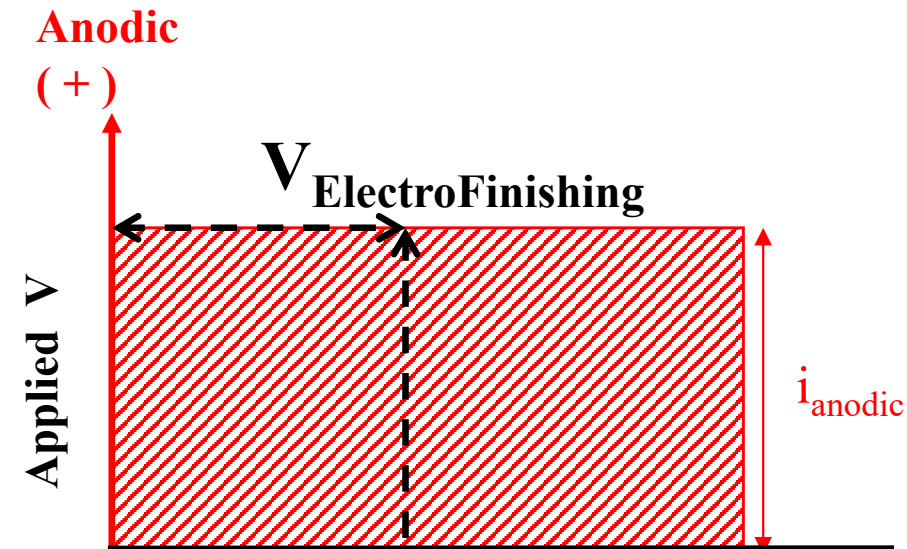




Pulse Surface Finishing

ElectroFinishing – Direct Current (DC)

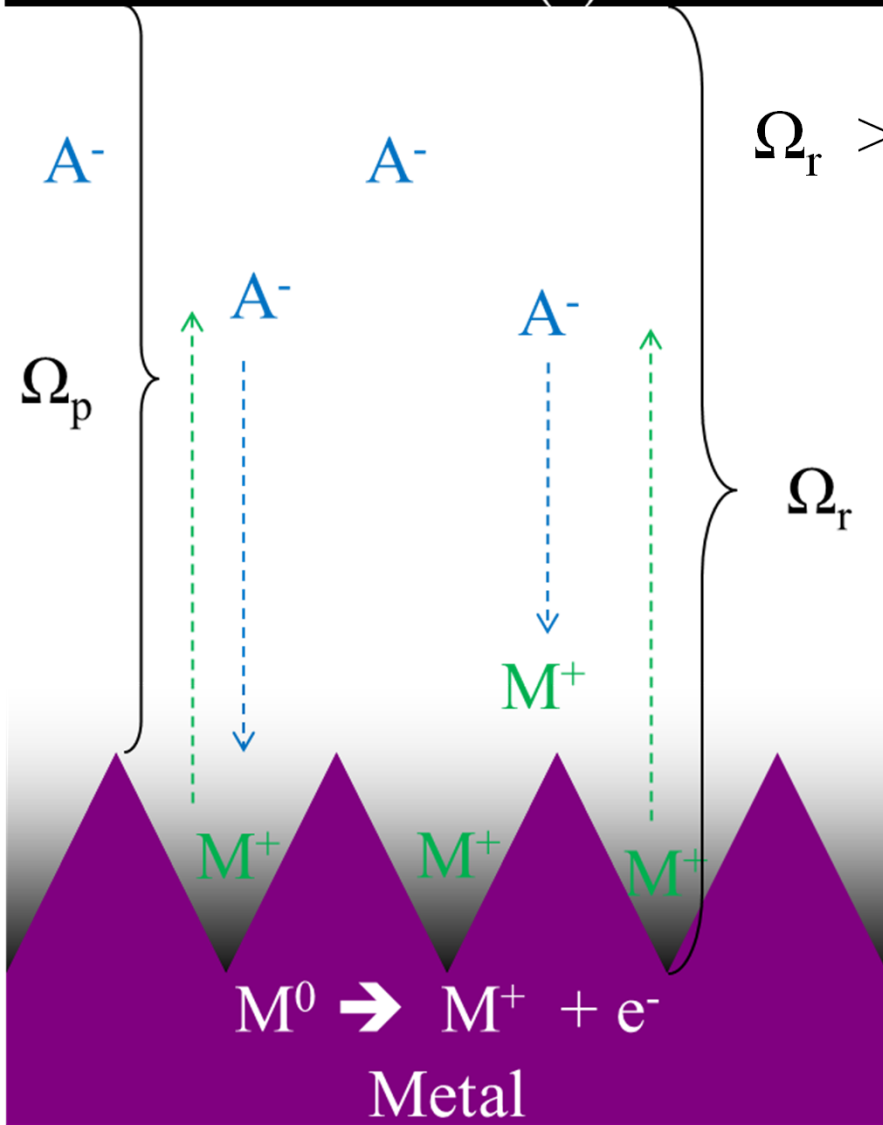
- Rectification:
 - DC - Constant voltage
 - Viscous salt film per Jacquet
 - Passive (oxide) film formation
- Electrolyte:
 - Concentrated/viscous acid
 - Chilled to increase viscosity
 - HF add to remove oxide



† P.A. Jacquet, *Trans. Electrochem. Soc.*, **69** 629 (1936).

Conventional (DC) Surface Finishing

Cathode (-)



DC Finishing Challenges:

1st Challenge: Current distribution, i.e. focusing current preferentially on peaks or asperities

- Large Features $> \sim 1 \mu\text{m}$ Macro-smoothing or leveling
- ➔ Chilled Resistive electrolytes
- Small Features $< \sim 1 \mu\text{m}$ Micro-smoothing or brightening
- ➔ Chilled Viscous electrolytes

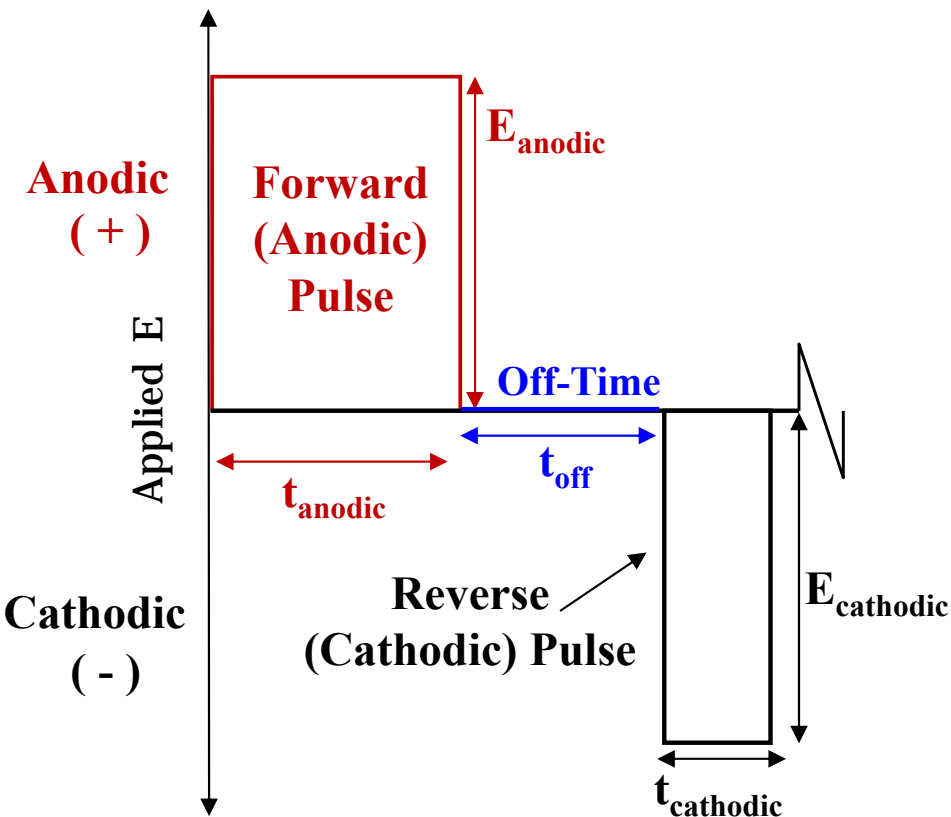
2nd Challenge: Polishing materials which form a passive (protective) or strongly passive layer



- Requires either water free or oxide preventing electrolyte (HF)

D. Landolt, Electrochimica Acta 32(1) 1-11 (1987).

Pulse/Pulse Reverse (P/PR) ElectroFinishing



Anodic Pulse – focus the current distribution to smooth surface

→ Eliminates need for viscous electrolyte

Cathodic Pulse – depassivates surface/
removal of surface oxide

→ Eliminate need for HF and/or low water content electrolytes

Off-time – no applied voltage

→ Dissipates heat – simplifies cell design

→ Replenishment of reacting species

→ Remove reaction products

P/PR ElectroFinishing shifts the paradigm → enabling use of aqueous, non-viscous electrolytes free of F⁻ /HF acid

1. E.J. Taylor, M. Inman, *The Electrochemical Society Interface* 23(3), 57, Fall 2014
2. M. Inman, E.J. Taylor, T. Hall, *J. Electrochem Soc* 160(9), E94-E98, 2013
3. E.J. Taylor, M. Inman, T. Hall, B. Kagajwala, *ECS Trans* 45(8), 13-20, 2013

P/PR ElectroFinishing Demonstrations

- Titanium Alloys
 - Nitinol (Ni:Ti 50:50)
 - Ti-15Mo
 - Ti-6Al-7Nb
 - **Ti-6Al-4V**
 - CP Ti (Grade 2/4)
- Mo
 - Pure Molybdenum
 - Spherical Mo-Hf
 - 52.5Mo-47.5Re
- Co-Cr
- **Nb**
- SAE 4159 Steel
- **Ta**
- Ta 10W
- **Cu**
- Stainless Steels
 - **316L**
 - 301/304
 - 430
 - C450
- Ni Alloys
 - **718 Inconel**
 - **625 Inconel**
 - Hastelloy
 - Haynes 230
- Aluminum Alloys
 - 6061
 - 7075

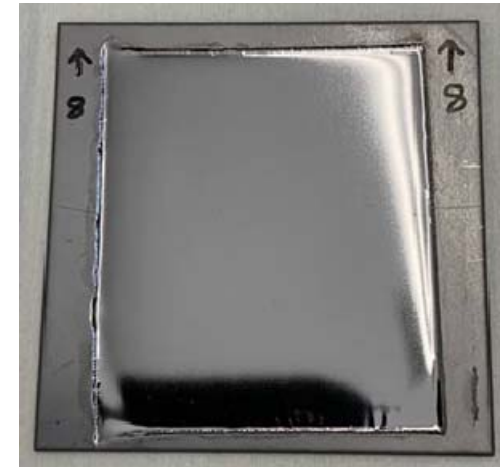
For P/PR (Generally);

$V_{\text{Anodic}} / V_{\text{Cathodic}} \rightarrow$ Material specific

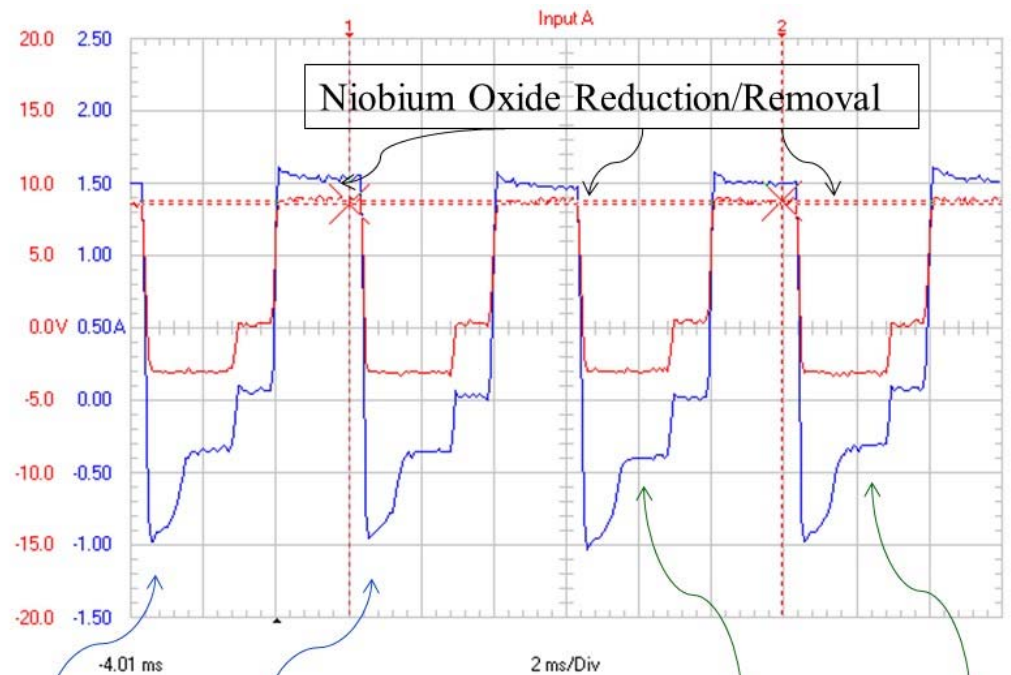
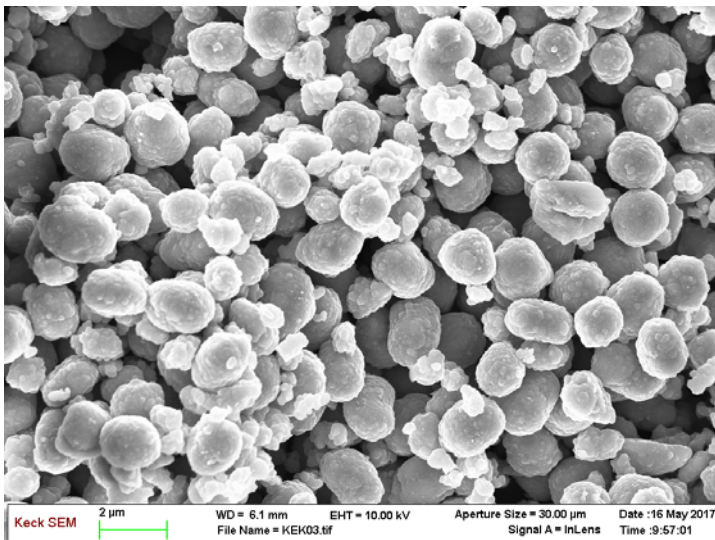
$t_{\text{anodic}} / t_{\text{cathodic}} / t_{\text{off}} \rightarrow$ Part/Cell geometry specific

Electropolish Passive Materials with Pulse

- Highly passive materials form strong oxides
 - Commonly electropolished in 9:1 H₂SO₄: HF
- Control of surface oxidation enable water-based EP
 - NaNO₃ and water
 - 5 w/w% H₂SO₄ and water
- Cathodic etching???



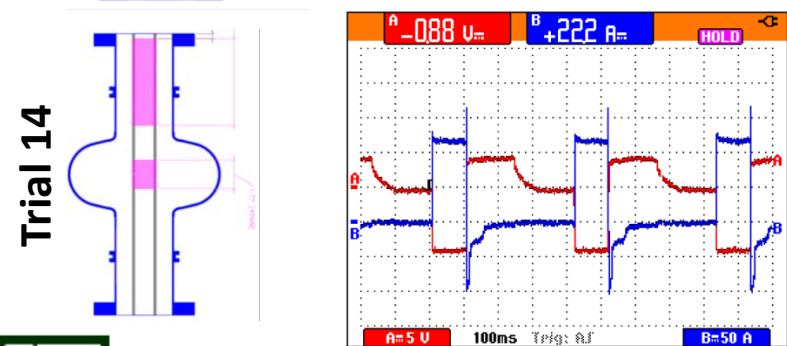
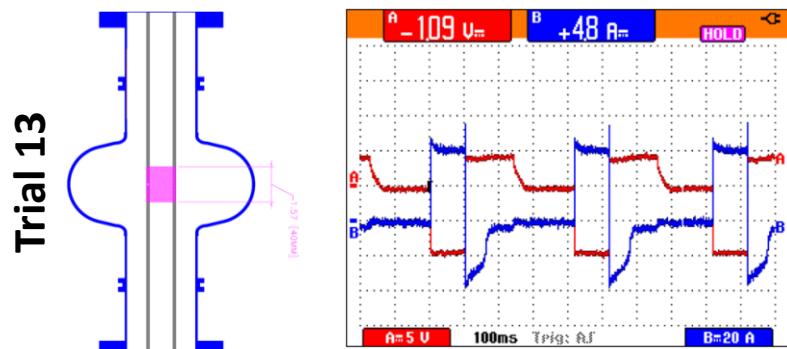
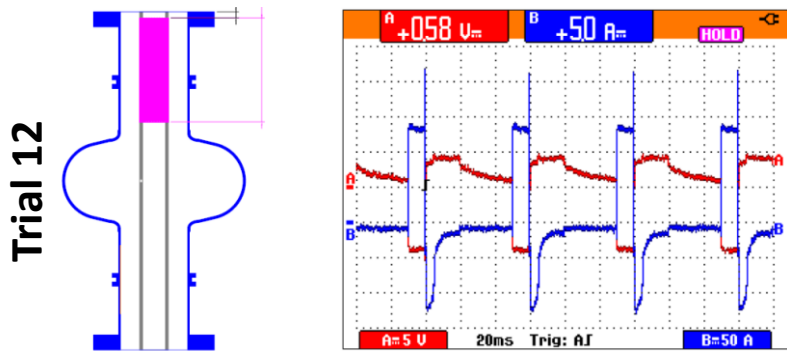
Resulting Nb Powder



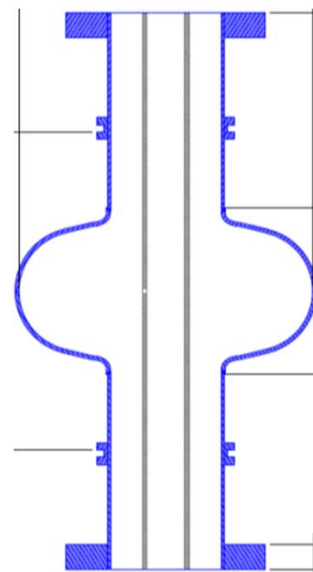
Electropolish Passive Materials with Pulse

Transition to complex cavity polishing

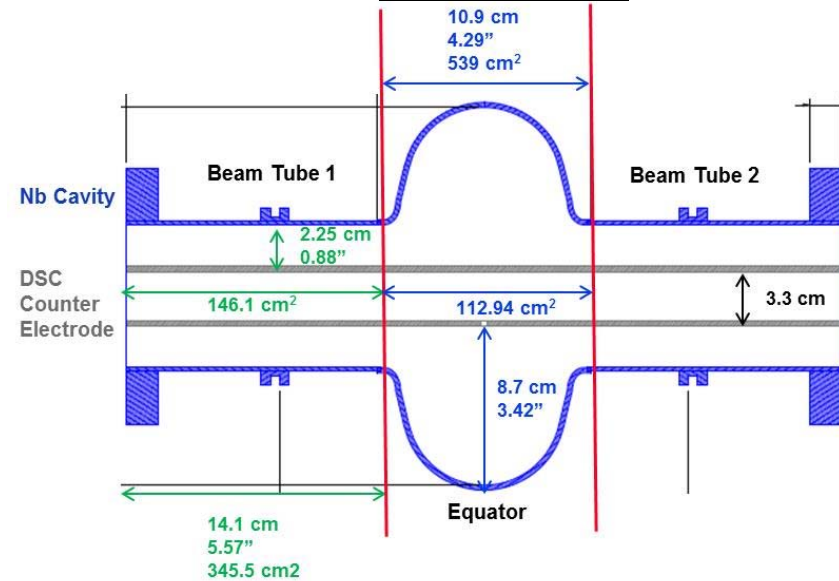
- Pink is open cathode area



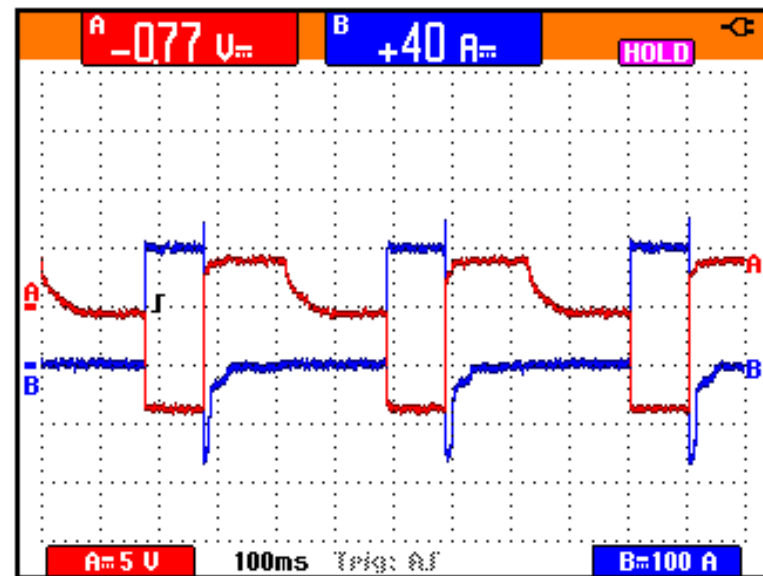
Trial 17



Cavity Shape



Unmasked Cavity

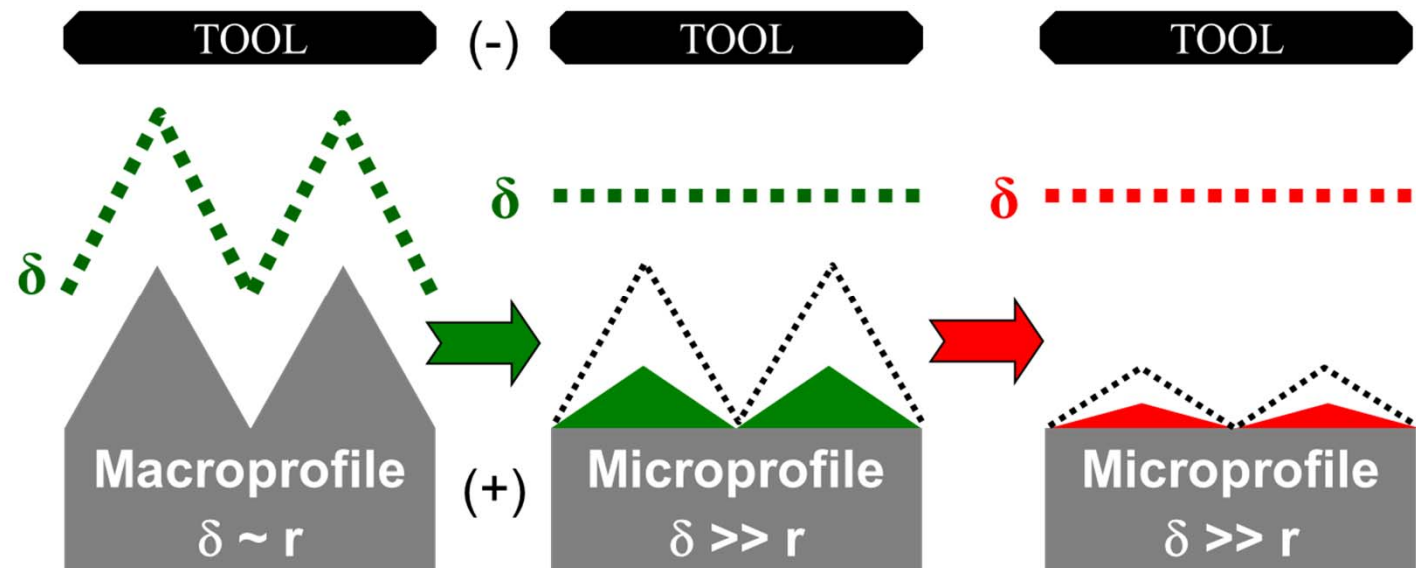


Finishing Complex Materials with Pulse

- Additively manufactured parts have a many levels roughness
 - As you finish the surface:
 - Surface area and profile height changes
 - Required boundary layer changes



❖ Design polishing conditions to accommodate changing surface



A. Karim et al, Physics Procedia, 78, 347-356 (2015)

Finishing Complex Materials with Pulse

➤ **CHALLENGE:** Improve $Ra < 2 \mu\text{m}$ while minimizing material removal

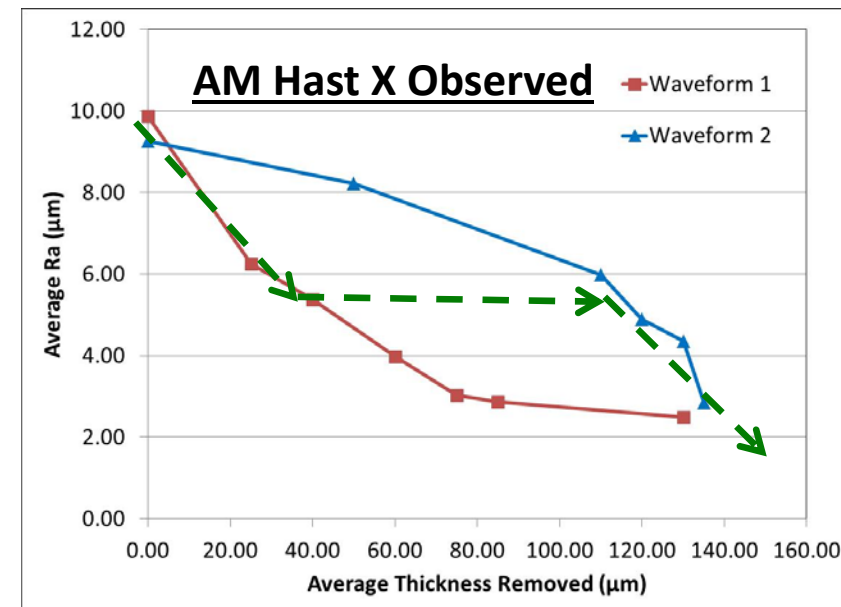
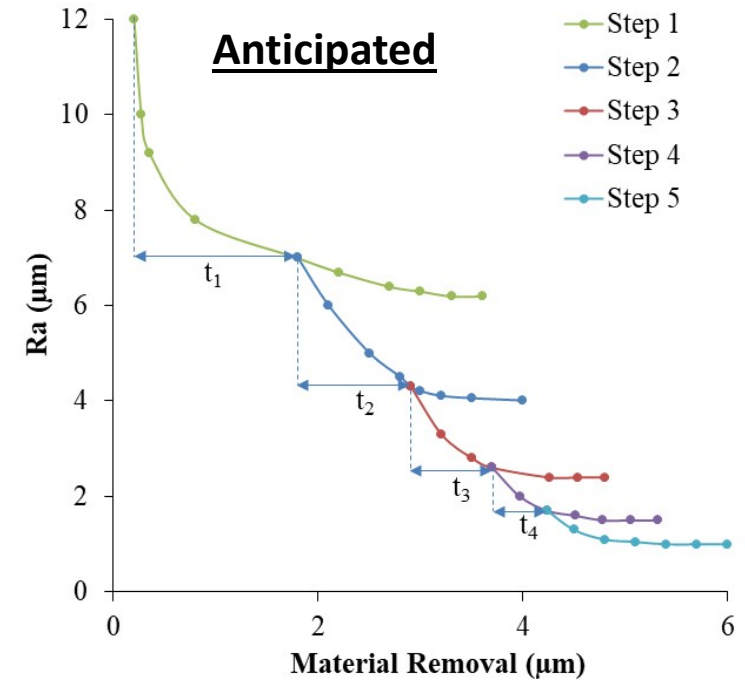
▪ **Waveform 1:**

- Initial rapid $\Delta Ra / \Delta \text{material removed}$ until $\sim 6 \mu\text{m}$ Ra reached
- Decrease in $\Delta Ra / \Delta \text{material removed}$ after $\sim 6 \mu\text{m}$ Ra reached

▪ **Waveform 2:**

- Initially slow $\Delta Ra / \Delta \text{material removed}$ until $\sim 6 \mu\text{m}$ Ra reached
- Increase in $\Delta Ra / \Delta \text{material removed}$ after $Ra < 6 \mu\text{m}$

➤ **SOLUTION:** Initiate process with Waveform 1 (4 min) until $Ra \sim 6 \mu\text{m}$ then switch to Waveform 2 (1 min) until next critical $Ra \sim 1.8$ with $80 \mu\text{m}$ removed.

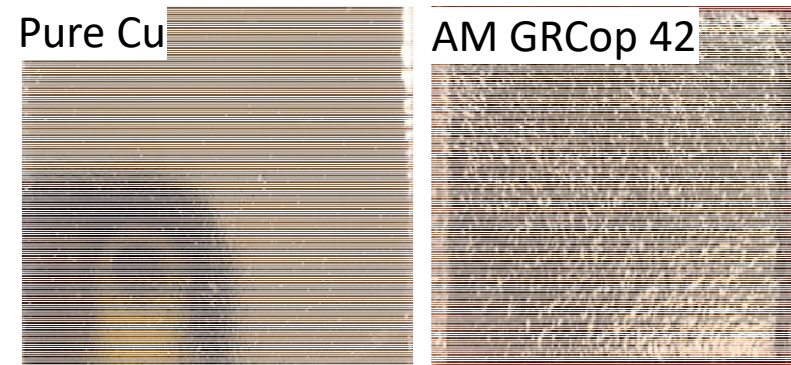


Electropolishing Precipitating Alloys

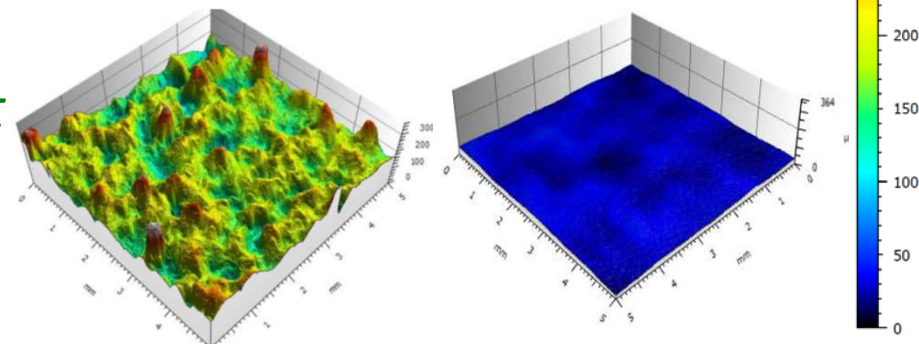
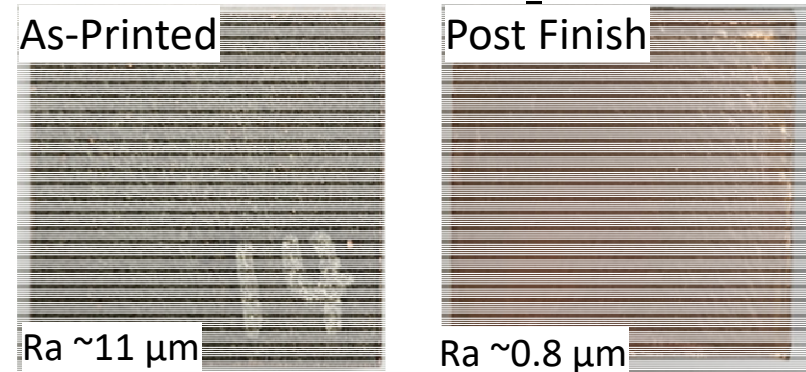
- GRCop 42
 - 0.06% Al; 3% Nb; 0.04% Si; 3.4% Cr; 0.03% Fe
- ❖ Complex alloys require special consideration
 - Nb/Al are passivating but low concentration
 - ❖ Must exceed breakdown voltage or provide *cathode breakdown*
 - Cr and Fe are known to ppt at surface
 - ❖ Must consider flow and off-time to control the movement of the ppt.

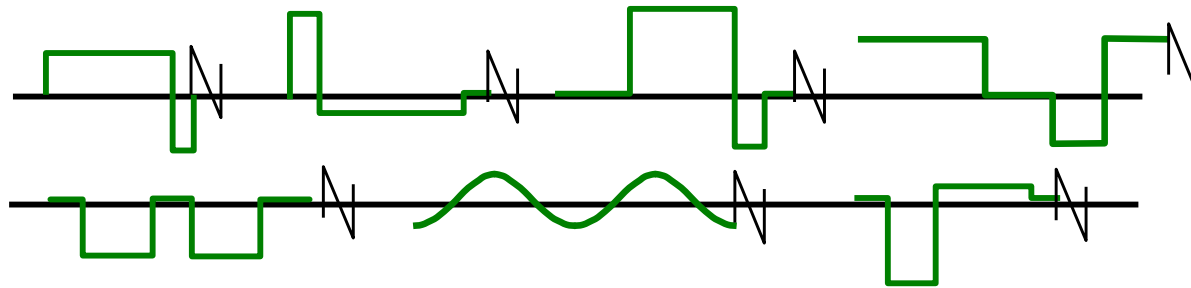
Changes in roughness leads to changes in ppt thickness and mobility

Electropolishing in SO_4/PO_4



AM GRCop 42 Electropolishing in $\text{NaCl}/\text{NaNO}_3$





What is next?

Electrodeposition

- Identify new alloys and materials
- Enable new performance properties
 - ❖ Electrical Resistance
 - ❖ Fatigue Resilience
 - ❖ Hardness
 - ❖ Corrosion Resistance
 - ❖ Embrittlement mitigating
 - ❖ Wear Resistance
 - ❖ Thermal Resistance
 - ❖ Thermal Expansion Match
 - ❖ Environmental Stewardship

1a	IIa	IIIa	IVa	Va	VIa	VIIa	VIII					1b	IIb	IIIb	IVb	Vb	VIb	VIIb	o				
1 H							Single metals that can be electrodeposited												2 He				
3 Li	4 Be																	5 B	6 C	7 N	8 O	9 F	10 Ne
11 Na	12 Mg																	13 Al	14 Si	15 P	16 S	17 Cl	18 Ar
19 K	20 Ca	21 SC	22 Ti	23 V	24 Cr	25 Mn	26 Fe	27 Co	28 Ni	29 Cu	30 Zn	31 Ga	32 Ge	33 As	34 Se	35 Br	36 Kr						
37 Rb	38 Sr	39 Y	40 Zr	41 Nb	42 Mo	43 Tc	44 Ru	45 Rh	46 Pd	47 Ag	48 Cd	49 In	50 Sn	51 Sb	52 Te	53 I	54 Xe						
55 Cs	56 Ba	57 La	72 Hf	73 Ta	74 W	75 Re	76 Os	77 Ir	78 Pt	79 Au	80 Hg	81 Tl	82 Pb	83 Bi	84 Po	85 At	86 Rn						

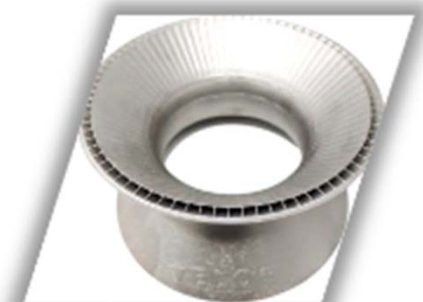
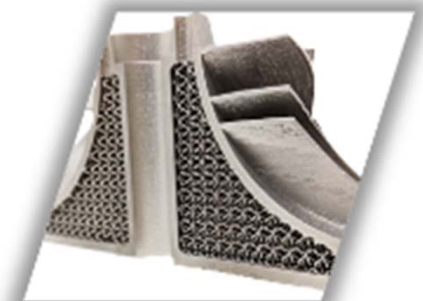
																		Au
																	Pt	X
																Ir	X	
															Re	X		
														W	X			X
													Sb	X			X	
												Sn	X	X			X	X
											In	X	X			X	X	
										Cd	X	X	X	X		X	X	
									Ag	X			X	X	X	X		
								Pd	X			X			X	X		
							Rh	X	X				X		X	X		
						Ru	X	X			X				X			
					Mo				X			X						
				Zr						X								
			Se						X	X			X					
		Zn	X	X	X				X	X	X	X	X	X				
	Cu	X	X	X			X	X	X	X	X	X	X	X				
	Ni	X	X	X			X	X	X	X	X	X	X	X				
	Co	X	X	X			X	X	X	X	X	X	X	X				
	Fe	X	X	X	X		X		X	X	X		X	X				
	Mn	X	X	X	X	X		X				X		X				
	Cr	X	X	X	X		X		X			X	X	X				
	V	X	X	X	X		X											
	Ti	X		X	X	X		X										

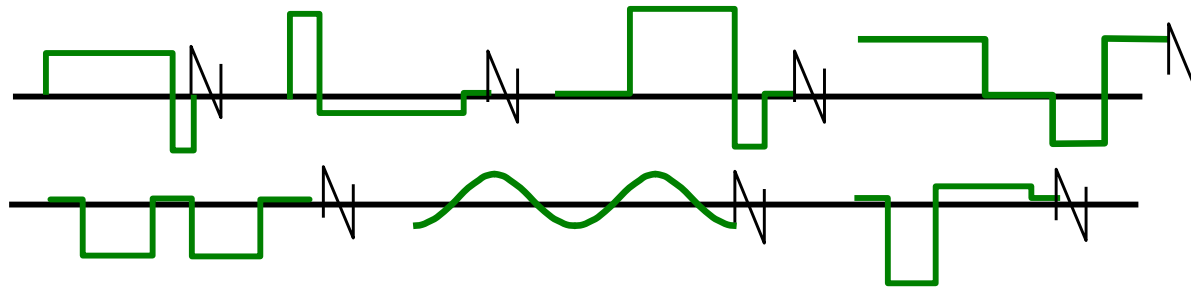
Eliasz, N., et al., *Modern Aspects of Electrochemistry* 42 Springer, NY, (2008), p 191, Ch. 4



Surface Finishing

- Enable operations with new AM based material systems
- Align existing manufacturing processes with new complex parts and structures
- Develop new software to predict operations and tool designs





Where is NASF and AESF?

Research Approach

- European View:

- Government funded interest led to:
 - German and France have master level programs to train and develop new techniques in electrochemical engineering (plating and finishing)



- US View:

- Broad range of electrochemical professors across the US
 - Very little funding to drive students to advance technologies in traditional electrofinishing



UBFC

UNIVERSITÉ
BOURGOGNE FRANCHE-COMTÉ

AESF

- Dr. William Blum's first lecture (1959):
 Education and the Electroplating Industry
- Key findings:
The society needs to educate apprentices, platers, works chemists/engineers, research chemists/engineers, plant executives, designers and the purchasing public
- AESF offers an extensive educational course load
 - These opportunities serve traditional plating industries
- AESF offers 4 University grant scholarships
 - These opportunities foster focused future research on advance technology needs for the community
- NASF leads the public education through lobbying activities



AESF/NASF Role in Surface Finishing Ecosystem

- An international organization
 - Encompassing BOTH US & European & Asian “research view”
- Unique membership
 - Symbiotic nature of industry and academia
- Develops educational content
 - Coursework and training for certification of today’s workforce
- Student scholarships & internships
 - Real world experience AND introduction to industry opportunities
- Research grants
 - Foundation for tomorrow’s innovative products/services
 - Introduction of student researchers to industry opportunities
 - Travel to SURFIN conferences

Next Steps

- Reach out and identify professors progressing our mission
- Learn more about opportunities in NASF/AESF
- Look to enable new opportunities to
 - Foster future mentors
 - Receive hands on experiences
 - Drive government funding

***In order to create one must first
question that which exists!!!***

Mentors, Colleagues, Collaborators, and Friends

